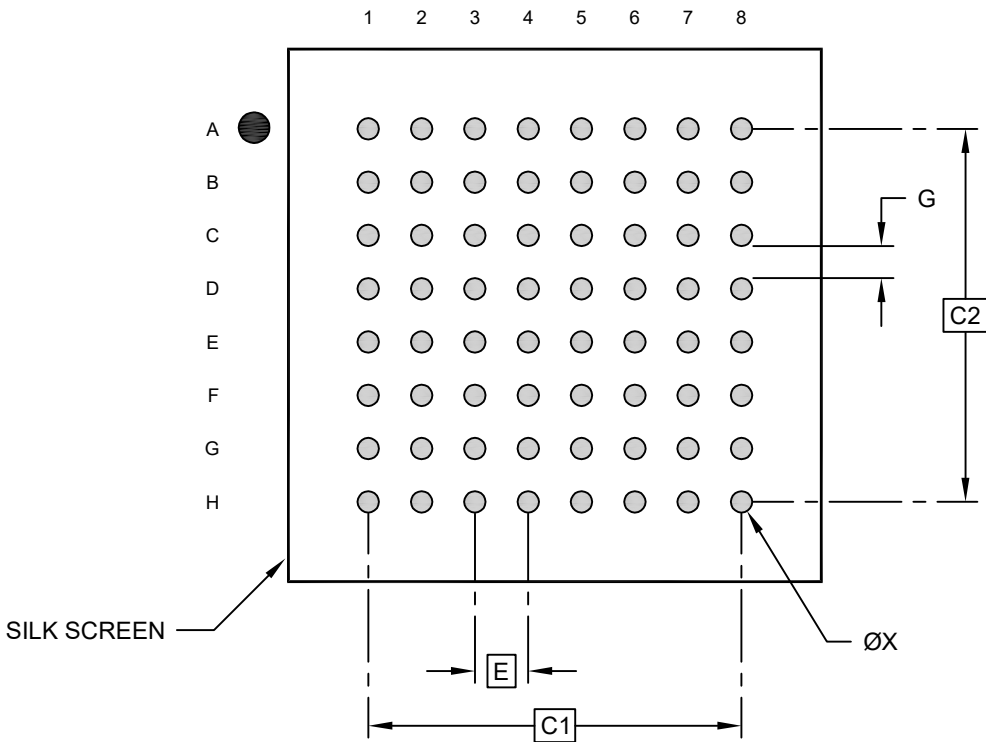


64-Ball Ultra Thin Fine-Pitch Ball Grid Array Package (BQB) - 5x5x0.65 mm Body [UFBGA]; Atmel Legacy Global Package Code CAH

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Contact Pitch	E		0.50 BSC		
Contact Pad Spacing	C1		3.50 BSC		
Contact Pad Spacing	C2		3.50 BSC		
Contact Pad Width (Xnn)	X				0.20
Contact Pad to Contact Pad (Xnn)	G		0.30		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.